



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 10/614,807
Filing Date July 9, 2003
Inventor Wuwen Yi et al.
Assignee Micron Technology, Inc.
Group Art Unit 1742
Examiner Harry D. Wilkins III
Attorney's Docket No. H0004116-US
Title: Copper Sputtering Targets and Methods of Forming Copper Sputtering
Targets

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

References -- See Attached Form PTO-1449

The attached form PTO-1449 is submitted in compliance with 37 CFR §1.56. No copies of any cited U.S. patents or U.S. published applications are included herewith. Copies of all other cited art are attached. No admission is made regarding whether all the submitted references are prior art.

Citation of these references is respectfully requested.

A check in the amount of \$180.00 is enclosed to cover the fee specified under 37 C.F.R. § 1.17(p).

Respectfully submitted,

Dated:

March 7, 2006

By:

Jennifer J. Taylor
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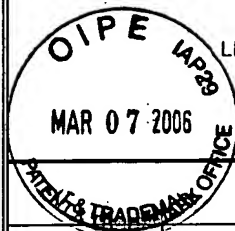
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PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
H0004116-USSERIAL NO.
10/614,807LIST OF ART CITED BY APPLICANT
(Use several sheets if necessary)APPLICANT
Wuwen Yi et al.FILING DATE
July 9, 2003GROUP
1742

U.S. PATENT DOCUMENTS

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	2002/0041819 A1	04/02	Kumar et al.			
	AB						
	AC						
	AD						
	AE						

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
	AF							
	AG							
	AH							
	AI							
	AJ							

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

	AK		V. Pavate et al., <i>Correlation between Aluminum alloy sputtering target metallurgical characteristics, Arc initiation, and In-film defect density</i> , pp. 42-47, SPIE Vol. 3214, 1997
	AL		
EXAMINER	DATE CONSIDERED		

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.